

Dallas Semiconductor Surface Mount Package Moisture Sensitivity Classification

PACKAGE TYPE	BODY SIZE	PIN COUNT	SnPb MSL	Pb-free MSL
BGA	27x27x1.73	256,300	4	N.Q.
BGA	27x27x1.5	272	4	N.Q.
BGA w/Crystal	11x9x2.44	24	4	N.Q.
BGA w/Crystal	11x10x4	36	4	N.Q.
BGA Module DS1254	40x40x8.0	168	4	N.Q.
BGA Module DS3816C-512 & DS3832	44x44x8.0	168	3	N.Q.
CSBGA	4x4x1	16	3	3
CSBGA	5x5x1	25	3	3
CSBGA	7x7x1	49	3	3
CSBGA	10x10x1	100	3	3
CSBGA-TE	13x13x1	144	3	N.Q.
CSBGA	14x14x1.26	169	3	N.Q.
CSBGA	17x17x1.26	256	3	N.Q.
CSBGA-TE	17x17x1.26	256	3	N.Q.
CSBGA	27x27x1.5	349	3	N.Q.
CSBGA Interposer	17x17x1.26	144	4	N.Q.
CSBGA Interposer	27x27x1.73	256	4	N.Q.
PBGA-TE	17x17x1.26	144	3	N.Q.
PBGA-TE	27x27x1.5	400	3	N.Q.
LQFP	7x7x1.4	48	3	3
LQFP	10x10x1.4	64	3	3
LQFP	14x14x1.4	100	4	4
LQFP	14x20x1.4	128	4	4
MQFP	10X10X2	44	3	N.Q.
MQFP	14x20x2.7	80,100	4	4
PLCC	450x450x3.9	28	1	1
PLCC	450x550x2.67	32	1	N.Q.
PLCC	650x650x3.87	44	3	3
PLCC	750x750x3.87	52	4	N.Q.
PLCC	950x950x3.87	68	4	N.Q.
POWER CAP	980x980x1.0	34	3	3
QFN	10x10x0.9	68	3	N.Q.
SOIC	150x1.4	8,14,16	1	1
SOIC	208x1.9	8	1	1
SOIC	300x2.3	16,20,24,28	1	1
SOIC w/Crystal	300x2.3	16	1	1
SOIC	330x2.3	28	3	1
SOT23	50x0.9	3	1	1
SOT23	60x1.2	5	1	1
SOT223	140x1.75	3	1	1
SSOP	5.3x1.75	16,24	1	1
SSOP	7.5x2.4	36	1	1
TQFN (TDFN)	3x3x0.8	6	1	1
TQFP	7x7x1	32,48	3	N.Q.
TQFP	10x10x1	44	4	3
TQFP	10x10x1	52,64	4	N.Q.
TSOC	150x1.25	6	1	1
TSOP	8x13x1	28	3	3
TSOP	8x20x1	32	3	3
TSSOP	4.4x0.9	8,14,16,20,24,28	1	1
uSOP	3x0.85	8,10	1	1

N.Q. - Not Qualified

(1) Exceptions are DS2180A & DS2181A which are MSL1 for SnPb only.

(2) Exceptions are DS1073, DS1075, DS1077, DS1077L, and DS1175 which are MSL4.

(3) Exception is DS17885 large pad which is MSL4.